

PR/161112 | Staff Process Engineer

募集職種

人材紹介会社
ジェイ エイ シー リクルートメント マレーシア

求人ID
1614217

業種
電気・電子・半導体

雇用形態
正社員

勤務地
マレーシア

給与
経験考慮の上、応相談

更新日
2026年11月03日 05:00

応募必要条件

職務経験
6年以上

キャリアレベル
中途経験者レベル

英語レベル
流暢レベル

日本語レベル
無し

最終学歴
短大卒： 準学士号

現在のビザ
日本での就労許可は必要ありません

募集要項

A leading global semiconductor organization is seeking a Staff Process Engineer to drive advanced packaging development and high-volume manufacturing for power semiconductor products. This role focuses on Power QFN (PQFN) and Cu clip-based thin die assembly processes, supporting both new product introduction and sustaining engineering. You will play a critical role in optimizing assembly processes, improving yield and cost efficiency, and ensuring robust production performance while collaborating closely with cross-functional teams and external manufacturing partners.

Key Responsibilities

- Lead package development and process qualification for PQFN (Power Quad Flat No-Lead) packages and Smart Power Stage (SPS) products.
- Develop and optimize assembly processes for thin wafer handling, die attach, and Cu clip technologies.
- Drive high-volume manufacturing ramp-up and qualify new production sources to meet capacity and demand requirements.

- Own sustaining engineering activities, continuously improving yield, quality, capacity, and cost performance.
- Collaborate with Product, Test, Quality, and Operations teams to resolve internal and customer-reported issues.
- Lead root cause analysis and implement corrective and preventive actions for process-related challenges.
- Manage and maintain Product Lifecycle Management (PLM) documentation to ensure accuracy and compliance.
- Drive suppliers change management initiatives to improve manufacturing robustness, scalability, and cost efficiency.
- Apply statistical methods (SPC, data analysis) to monitor performance and drive continuous improvements.

Key Requirements

- Bachelor's degree in Mechanical, Materials, Physics, Chemistry, or Applied Sciences (or related discipline).
- Proven experience in semiconductor process engineering or advanced packaging development.
- Strong experience with PQFN, QFN, WLCSP, or similar package technologies.
- Knowledge of thin wafer handling, die attach, and Cu clip assembly processes (especially for power devices).
- Understanding of quality and reliability requirements for semiconductor packaging.
- Hands-on experience with statistical process control (SPC) and data analysis tools (e.g., JMP).
- Strong problem-solving, analytical, and project management skills.
- Effective communication and stakeholder management skills in a cross-functional environment.
- Ability to manage complex projects and drive outcomes in a fast-paced manufacturing environment.

Notice: By submitting an application for this position, you acknowledge and consent to the disclosure of your personal information to the Privacy Policy and Terms and Conditions, for the purpose of recruitment and candidate evaluation.

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会社説明